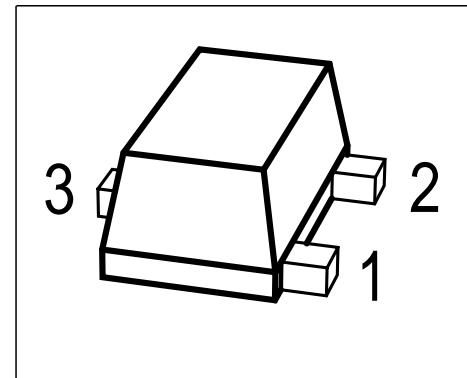


NPN Silicon RFTransistor

Preliminary data

- Low voltage/ low current operation
- Transistor frequency of 14 GHz
- High insertion gain
- Ideal for low current amplifiers and oscillators



ESD: Electrostatic discharge sensitive device, observe handling precaution!

Type	Marking	Pin Configuration			Package
BFR340F	FAs	1 = B	2 = E	3 = C	TSFP-3

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}	6	V
Collector-base voltage	V_{CBO}	17	
Emitter-base voltage	V_{EBO}	2	
Collector current	I_C	10	mA
Base current	I_B	2	
Total power dissipation ¹⁾ $T_S \leq 118^\circ\text{C}$	P_{tot}	60	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Ambient temperature	T_A	-65 ... 150	
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Junction - soldering point ²⁾	R_{thJS}	≤ 530	K/W
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¹ T_S is measured on the collector lead at the soldering point to the pcb.

² For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage $I_C = 1 \text{ mA}, I_B = 0$	$V_{(\text{BR})\text{CEO}}$	6	9	-	V
Collector-base cutoff current $V_{CB} = 5 \text{ V}, I_E = 0$	I_{CBO}	-	-	100	nA
Emitter-base cutoff current $V_{EB} = 1 \text{ V}, I_C = 0$	I_{EBO}	-	-	1	μA
DC current gain $I_C = 5 \text{ mA}, V_{CE} = 2 \text{ V}$	h_{FE}	70	100	200	-

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics (verified by random sampling)					
Transition frequency $I_C = 6 \text{ mA}, V_{CE} = 3 \text{ V}, f = 1 \text{ GHz}$	f_T	12	14	-	GHz
Collector-base capacitance $V_{CB} = 5 \text{ V}, 1 \text{ MHz}, \text{emitter grounded}$	C_{cb}	-	0.21	0.4	pF
Collector-emitter capacitance $V_{CE} = 5 \text{ V}, 1 \text{ MHz}, \text{base grounded}$	C_{ce}	-	0.17	-	
Emitter-base capacitance $V_{EB} = 0.5 \text{ V}, 1 \text{ MHz}, \text{collector grounded}$	C_{eb}	-	0.11	-	
Noise figure $V_{CE} = 3 \text{ V}, I_C = 1 \text{ mA}, f = 1.8 \text{ GHz}, Z_S = Z_{\text{Sopt}}$	F_{min}	-	1.15	-	dB
Power gain ¹⁾ $V_{CE} = 3 \text{ V}, I_C = 5 \text{ mA}, f=1.8\text{GHz}, Z_S=Z_{\text{Sopt}}, Z_L=Z_{\text{Lopt}}$ $V_{CE} = 3 \text{ V}, I_C = 5 \text{ mA}, f=3\text{GHz}, Z_S=Z_{\text{Sopt}}, Z_L=Z_{\text{Lopt}}$	G_{ms} G_{ma}	-	16	-	
Insertion power gain $V_{CE} = 3 \text{ V}, I_C = 5 \text{ mA}, f= 1.8\text{GHz}, Z_S = Z_{\text{Sopt}} = 50\Omega$ $V_{CE} = 3 \text{ V}, I_C = 5 \text{ mA}, f= 3\text{GHz}, Z_S = Z_{\text{Sopt}} = 50\Omega$	$ S_{21} ^2$	-	13	-	
Third order intercept point at output ²⁾ $V_{CE} = 3 \text{ V}, I_C = 5 \text{ mA}, f= 1.8\text{GHz}, Z_S = Z_{\text{Sopt}} = 50\Omega$	OIP_3	-	12	-	dBm
1 dB Compression point at output ³⁾ $V_{CE} = 3 \text{ V}, I_C = 5 \text{ mA}, f= 1.8\text{GHz}, Z_S = Z_{\text{Sopt}} = 50\Omega$	$P_{-1\text{dB}}$	-	0	-	

¹ $G_{\text{ma}} = |S_{21} / S_{12}| (\kappa - (\kappa^2 - 1)^{1/2})$; $G_{\text{ms}} = |S_{21} / S_{12}|$

² IIP_3 value depends on termination of all intermodulation frequency components.

Termination used for this measurement is 50Ω from 0.1 MHz to 6 GHz

³DC current at no input power

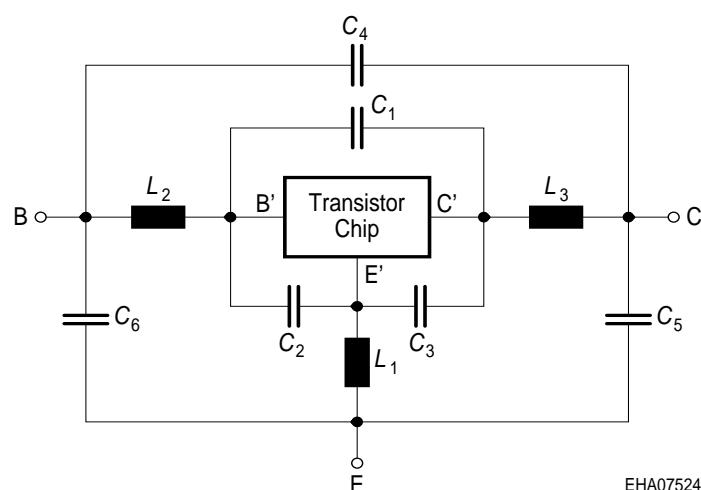
SPICE Parameters (Gummel-Poon Model, Berkley-SPICE 2G.6 Syntax) :
Transistor Chip Data

IS =	6.12	fA	BF =	98.48	-	NF =	0.4213	-
VAF =	42.228	V	IKF =	103	mA	ISE =	11.768	nA
NE =	2.4753	-	BR =	19.61	-	NR =	0.3253	-
VAR =	16.777	V	IKR =	0.834	A	ISC =	3.632	nA
NC =	0.8956	-	RB =	59.99	Ω	IRB =	0.01	mA
RBM =	0.2403	Ω	RE =	3.677		RC =	5.2493	Ω
CJE =	182	fF	VJE =	0.626	V	MJE =	0.4172	-
TF =	10.3	ps	XTF =	0	-	VTF =	0.262	V
ITF =	0.0017	mA	PTF =	0	deg	CJC =	222.63	fF
VJC =	0.5487	V	MJC =	0.319	-	XCJC =	0.3904	-
TR =	2.71	ns	CJS =	0	fF	VJS =	0.75	V
MJS =	0	-	NK =	0.5	-	EG =	1.11	eV
XTI =	0	-	FC =	0.735	-	TNOM	300	K

All parameters are ready to use, no scaling is necessary.

Extracted on behalf of Infineon Technologies AG by:

Institut für Mobil- und Satellitentechnik (IMST)

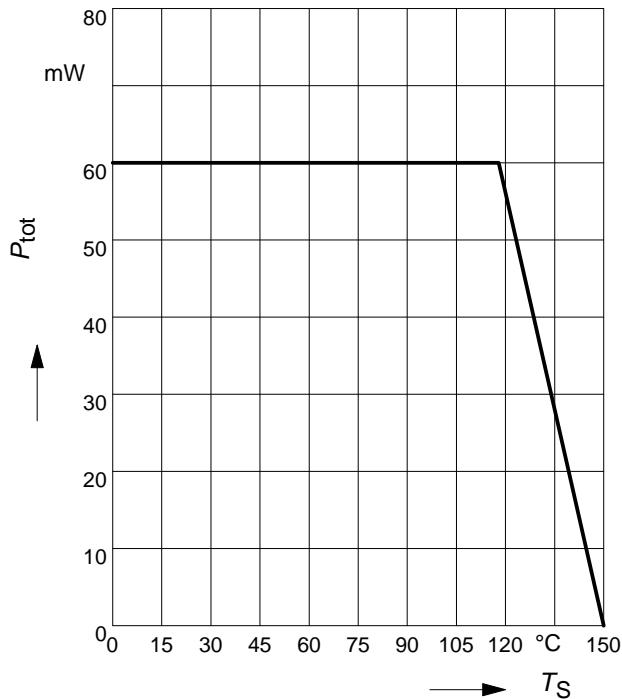
Package Equivalent Circuit:


L_1 =	0.556	nH
L_2 =	0.657	nH
L_3 =	0.381	nH
C_1 =	43	fF
C_2 =	123	fF
C_3 =	66	fF
C_4 =	10	fF
C_5 =	36	fF
C_6 =	47	fF

Valid up to 6GHz

For examples and ready to use parameters please contact your local Infineon Technologies distributor or sales office to obtain a Infineon Technologies CD-ROM or see Internet: <http://www.infineon.com/silicondiscretes>

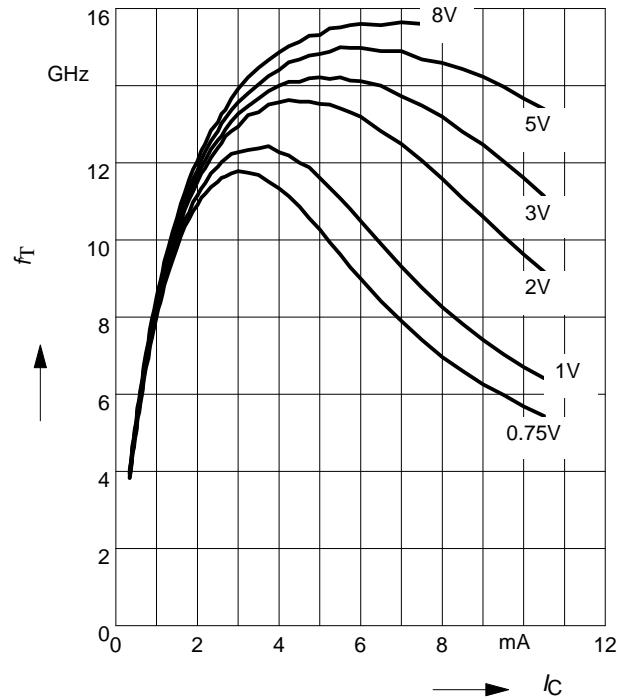
Total power dissipation $P_{\text{tot}} = f(T_S)$



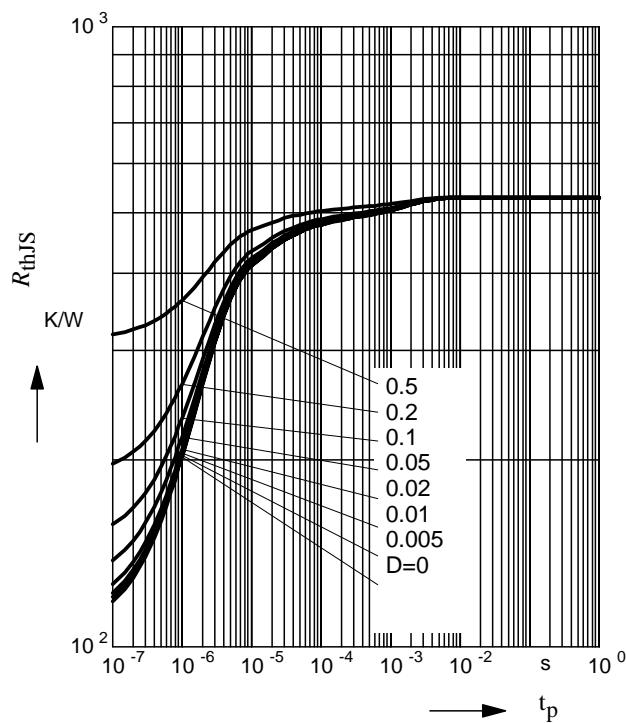
Transition frequency $f_T = f(I_C)$

$f = 1\text{GHz}$

V_{CE} = Parameter

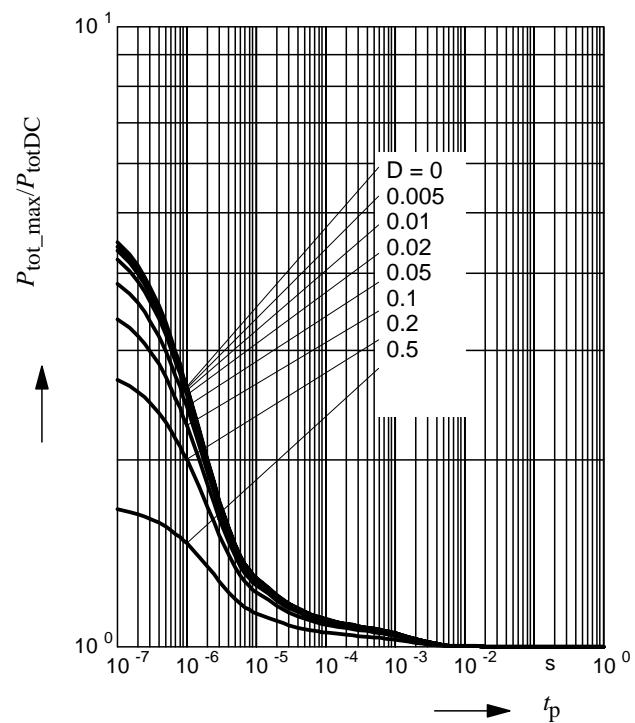


Permissible Pulse Load $R_{\text{thJS}} = f(t_p)$

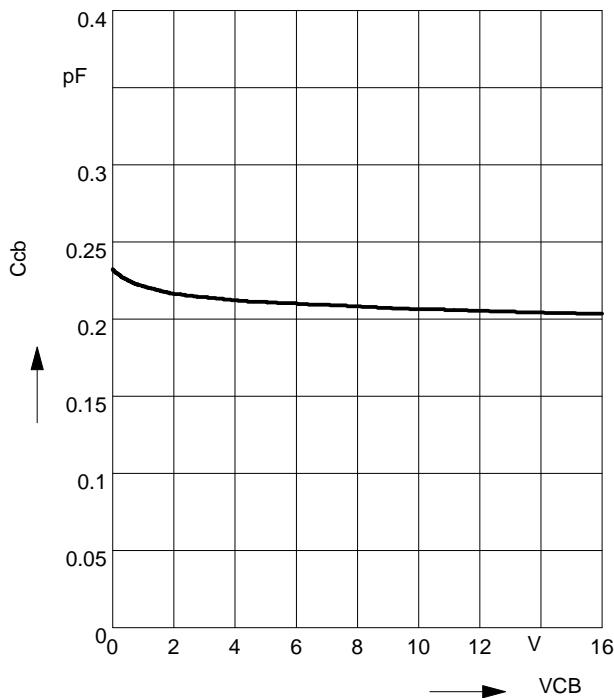


Permissible Pulse Load

$P_{\text{tot_max}}/P_{\text{totDC}} = f(t_p)$



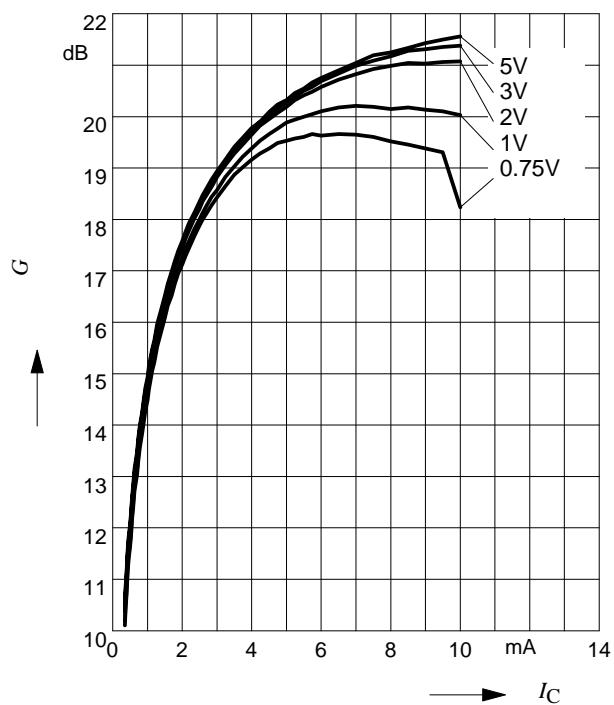
Collector-base capacitance $C_{cb} = f(V_{CB})$
 $f = 1\text{MHz}$



Power Gain $G_{ma}, G_{ms} = f(I_C)$

$f = 0.9\text{GHz}$

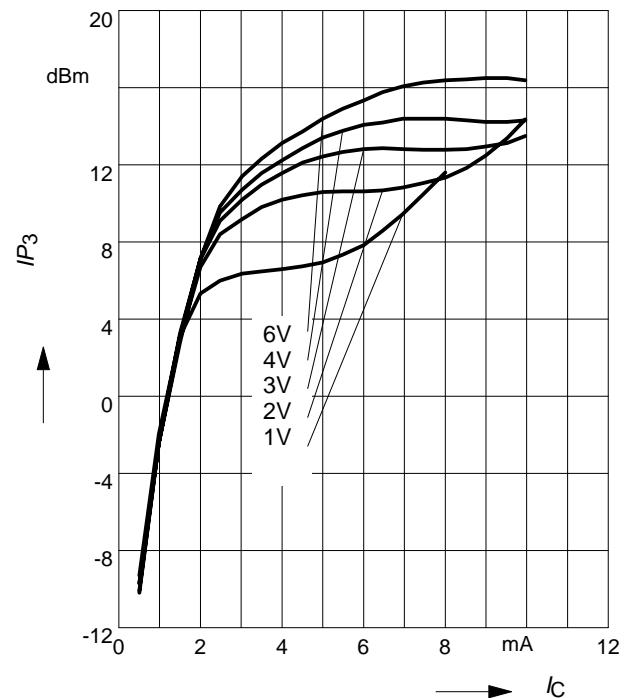
V_{CE} = Parameter



Intermodulation Intercept Point $IP_3=f(I_C)$

(3rd order, Output, $Z_S=Z_L=50\Omega$)

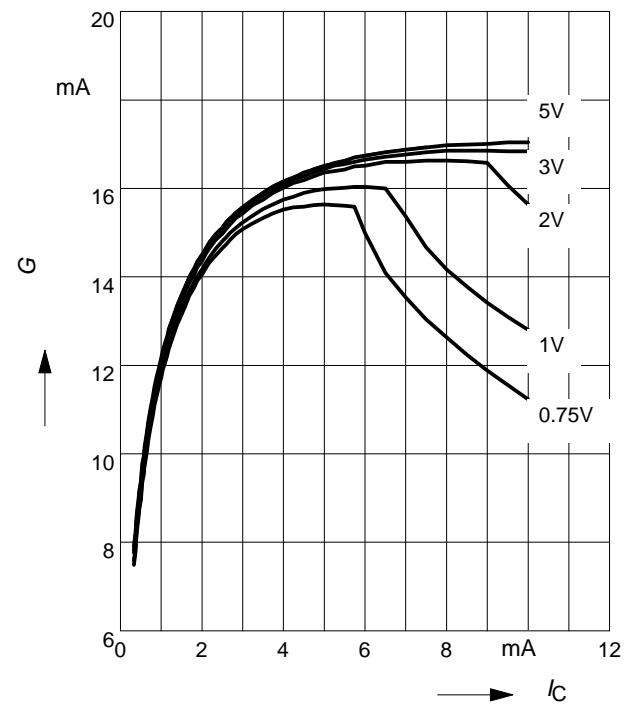
V_{CE} = Parameter, $f = 1.8\text{GHz}$



Power Gain $G_{ma}, G_{ms} = f(I_C)$

$f = 1.8\text{GHz}$

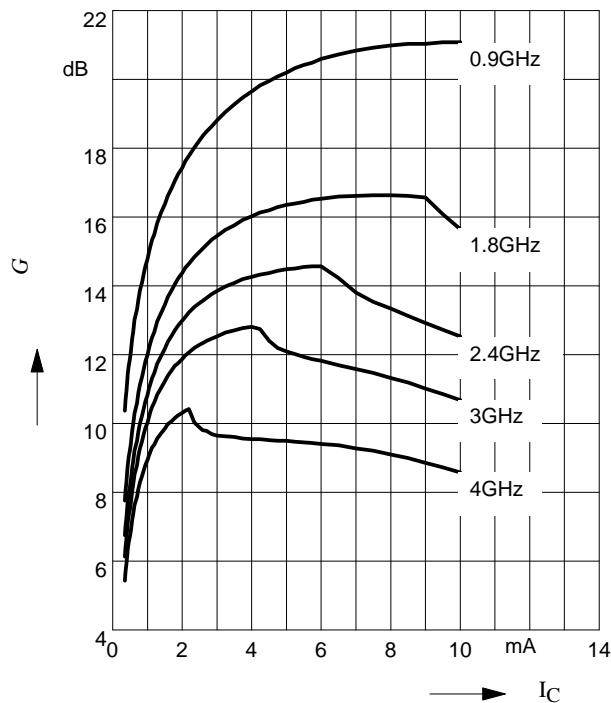
V_{CE} = Parameter



Power gain $G_{ma}, G_{ms} = f(I_C)$

$V_{CE} = 2V$

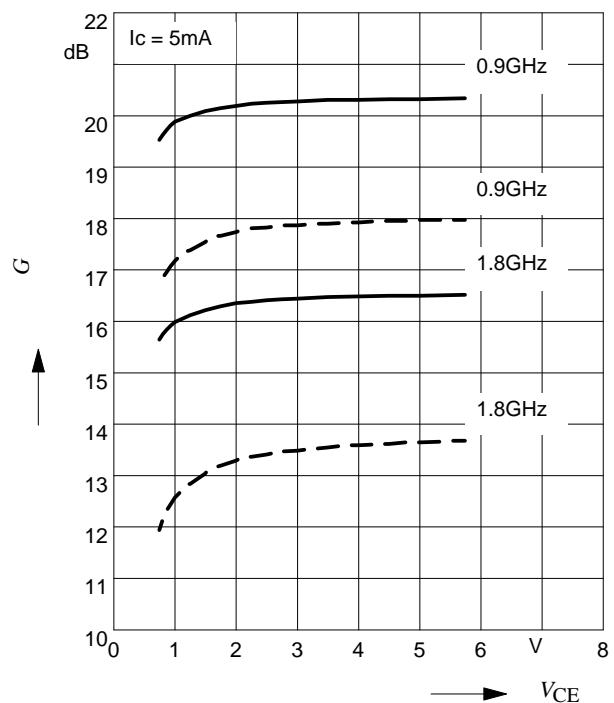
$f = \text{Parameter}$



Power Gain $G_{ma}, G_{ms} = f(V_{CE})$: _____

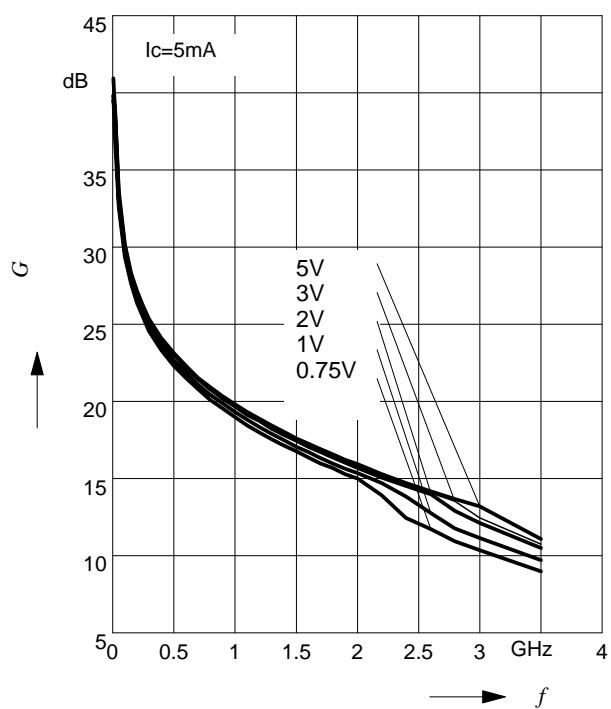
$|S_{21}|^2 = f(V_{CE})$: -----

$f = \text{Parameter}$



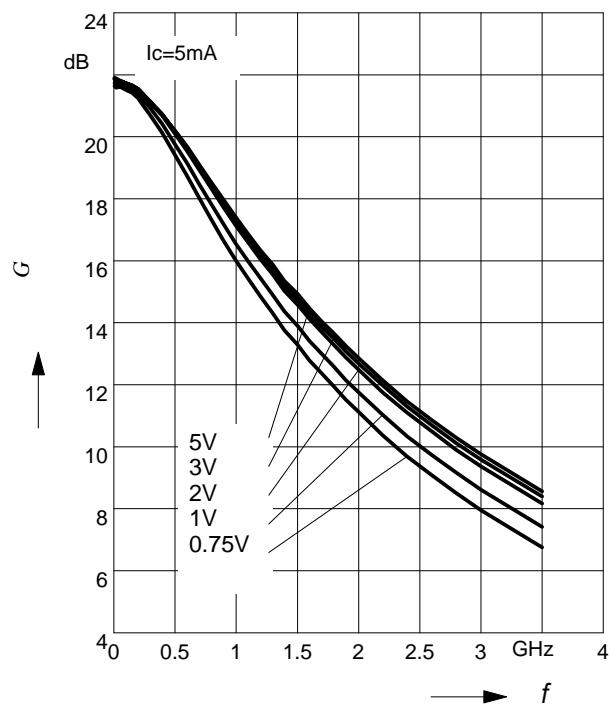
Power Gain $G_{ma}, G_{ms} = f(f)$

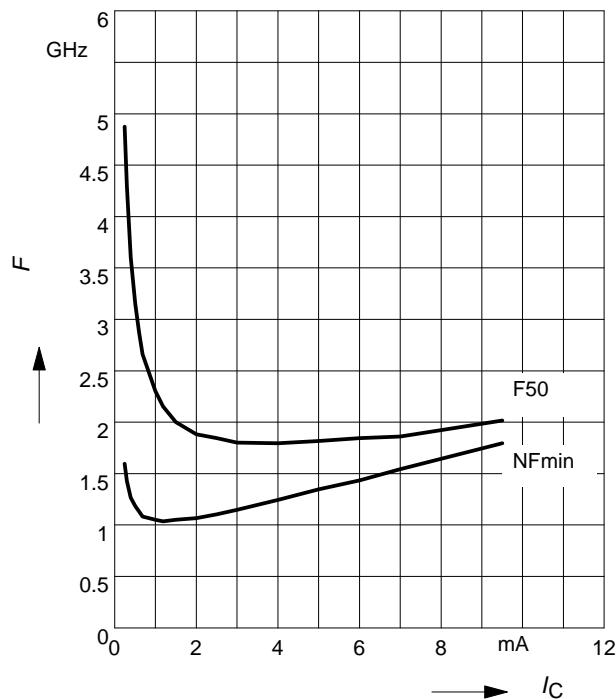
$V_{CE} = \text{Parameter}$



Power gain $|S_{21}|^2 = f(f)$

$V_{CE} = \text{Parameter}$



Noise figure $NF = f(f)$
 $V_{CE} = 3V, f = 1.8\text{GHz}$

Source impedance for min.
noise figure vs. Frequency
 $V_{CE} = 3 \text{ V}$
